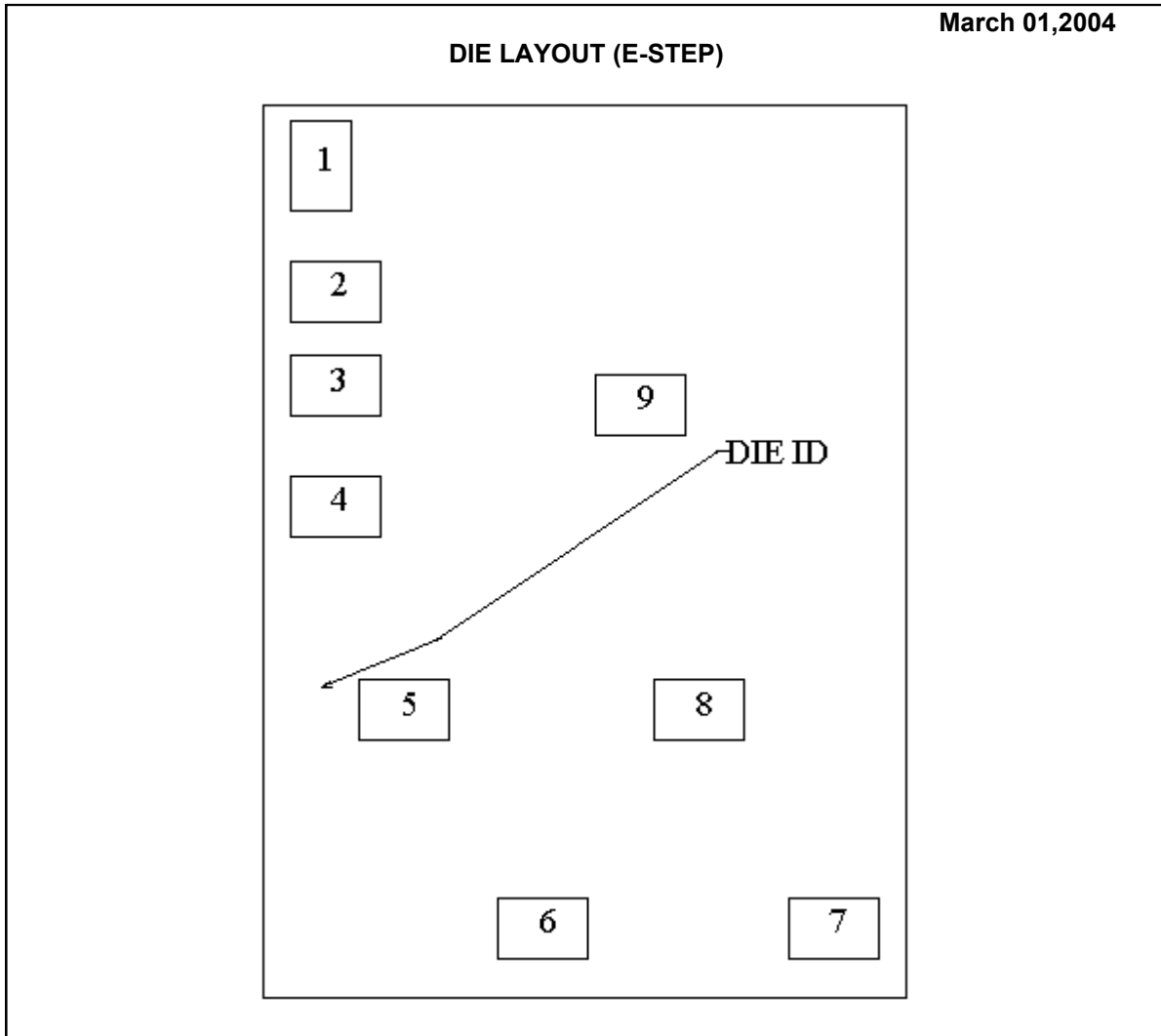


**LM1875 MDC MWC
20W AUDIO POWER AMPLIFIER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1875E	Bond Pad Opening Size (min)	381 μ m x 257 μ m
Die Step	E	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TI,NI,AG
Die Size (Drawn)	3785 μ m x 2718 μ m 149.0mils x 107.0mils	Back Side Connection	GND
Thickness	254 μ m Nominal		
Min Pitch	402 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (E -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
+IN	1	-1118	1633	254	x	381
-IN	2	-1054	1102	381	x	254
-VEE	3	-1054	700	381	x	257
-VEE	4	-1054	191	381	x	254
OUTPUT	5	-762	-673	381	x	254
VCC	6	-175	-1600	381	x	254
VCC	7	1054	-1600	381	x	254
OUTPUT	8	488	-673	381	x	254
-VEE	9	239	620	381	x	254

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